

Features

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 3 and 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOD-323
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Leads: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: Cathode Band
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.004 grams (approximate)

SOD-323



TOP VIEW

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{R(RM)}	75	V
Working Peak Reverse Voltage	V _{R(WM)}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current	I _{FM}	500	mA
Average Rectified Output Current	I _O	250	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0μs	4.0
		@ t = 1.0s	2.0

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 2)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V _{(BR)R}	75	—	V	I _R = 2.5μA
Forward Voltage	V _{FM}	0.62	0.72	V	I _F = 5.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 100mA
		—	1.25		I _F = 150mA
Peak Reverse Current (Note 1)	I _{RM}	—	2.5	μA	V _R = 75V
			50	μA	V _R = 75V, T _J = 150°C
			30	μA	V _R = 25V, T _J = 150°C
			25	nA	V _R = 20V
Total Capacitance	C _T	—	4.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes:
1. Short duration pulse test used to minimize self-heating.
 2. Part mounted on FR-4 PC board with minimum recommended pad layouts, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. No purposefully added lead. Halogen and Antimony Free.
 4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

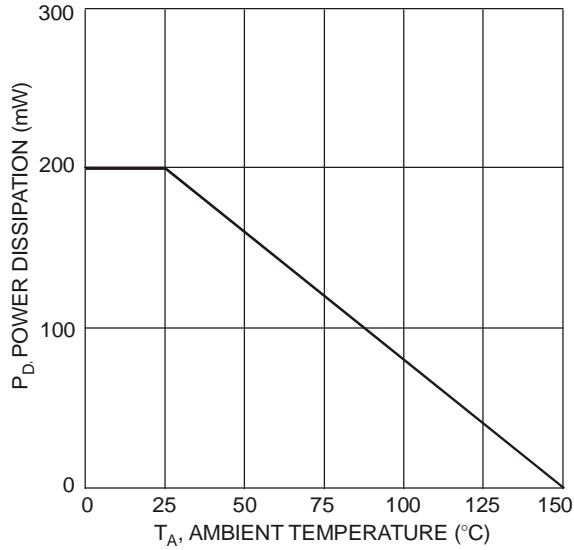


Fig. 1 Forward Current Derating Curve

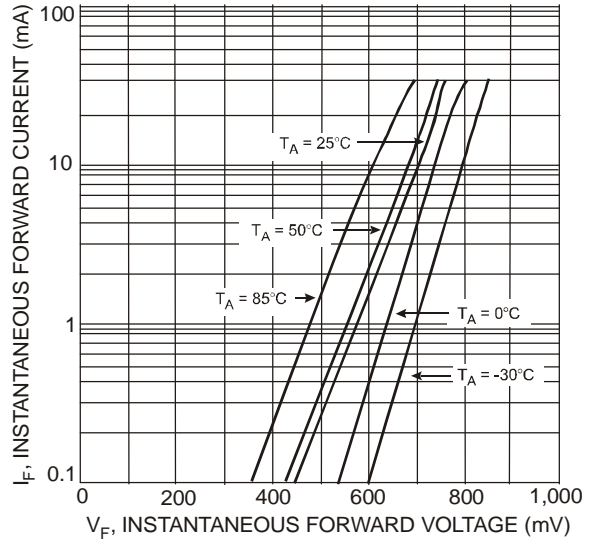


Fig. 2 Typical Forward Characteristics

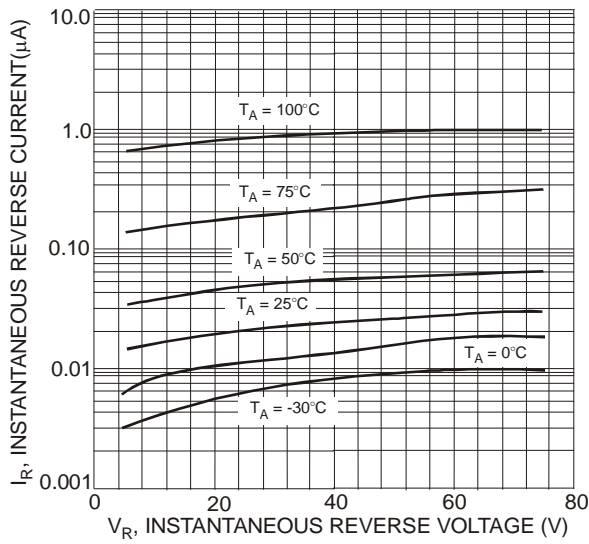


Fig. 3 Typical Reverse Characteristics

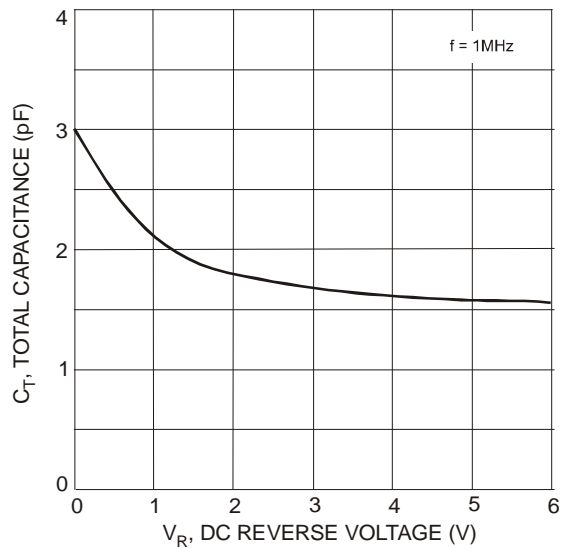


Fig. 4 Total Capacitance vs. Reverse Voltage

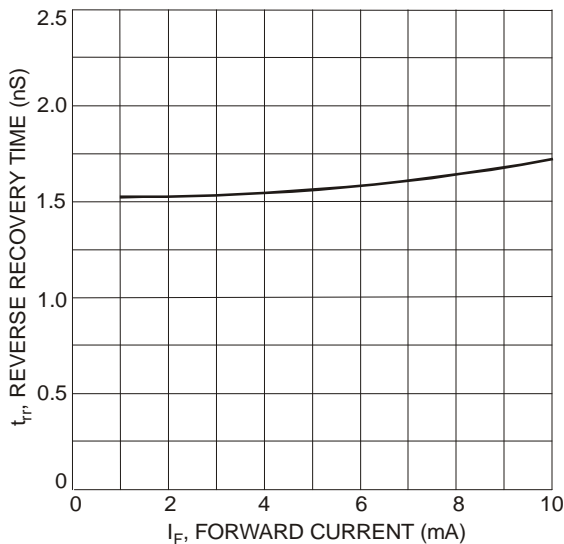


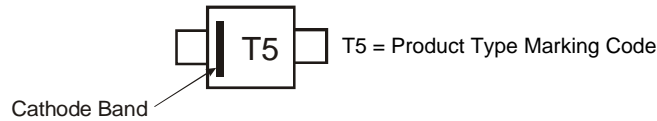
Fig. 5 Reverse Recovery Time vs. Forward Current

Ordering Information (Note 5)

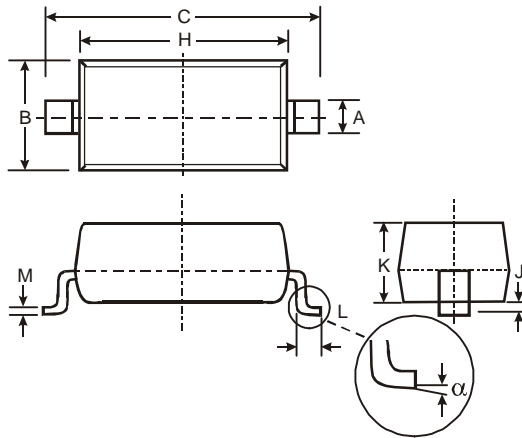
Part Number	Case	Packaging
1N4448WS-7-F	SOD-323	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

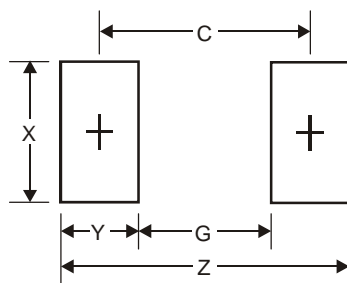


Package Outline Dimensions



SOD-323		
Dim	Min	Max
A	0.25	0.35
B	1.20	1.40
C	2.30	2.70
H	1.60	1.80
J	0.00	0.10
K	1.0	1.1
L	0.20	0.40
M	0.10	0.15
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.75
G	1.05
X	0.65
Y	1.35
C	2.40

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